5430

Manual and Semi-automatic Wire Bonder

The user-programmable wedge-wedge bonder 5430 can process aluminium and gold wires from 17.5 to 75 µm diameter. The compact desk-top unit is ideal for small-scale production, laboratory, prototyping, pre-series and for repair applications. The stepping motor driven Y and Z axes enable single or multiple bonds to be executed reliable and repeatable under full programme control. Operators require only a minimum of traiing, making the 5430 the ideal choice for pre-series and small-scale production.

The highly flexible 5430 can be used for multiple applications and the bond head is easily exchangeable allowing technology mixes, e.g. deep access.

Specifications

Technology	Stepper motor driven Y and Z axes Single board PC controller, menu programming BPC 2000 on-line bond process control unit (optional)
Wire Types	17.5 to 75 µm diameter gold & aluminium wire on 2" spool
Bond Head	Wire guide 45˚/60˚ wire feed optional Electronic touchdown sensing for every bond Programmable output ultrasonic system, 0 to 5 W, 60 or 100 kHz, other frequencies optional Programmable bond force 15 to 150 cN Conversion kit for fine wire ball and/or heavy wire wedge bonding available
Working Area	Y axis: 50 mm, Z axis: 50 mm; 2.5 µm resolution Standard work height 136 mm (mid Z stroke) X/Y manipulator from 5x5 mm to 18x18 mm Equivalent manipulator step-down 1:2 to 1:7
Work Holder	Standard 60 mm ∅ for parts up to 2" x 2 Optionally: 4" x 4" and 80 mm ∅, mechanical and vacuum clamping, heated work holder with digital temperature control up to 360˚ C
Operating Modes	Manual, semi-automatic, automatic, multi-wire Step mode for programme debug
Loop Forms	Standard rectangular, standard triangular, single and double reverse, stitch; clamp and table tear
Programme Memory	Up to 50 individual wires per programme, 250 programmes per 3.5“ floppy disk, can be edited and printed as text files via PC
Dimensions	Height 50 cm, width 60 cm, depth 60 cm, approx. 55 kg
Supplies	100 to 230 VAC, single-phase; air/vacuum 7 mm ∅ connector if necessary

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